

ABSTRACT OF THE DISCLOSURE

A substrate (2) is composed of laminated green sheets. The substrate (2) is provided with recesses (2f, 2g) formed on at least two locations deeper than implemented heights of ICs (4, 6) and elements (3, 5). A transmitter and a receiver are mounted in different recesses, which are individually covered with a mold resin to form a molded optical communication module (1), which operates fast and causes no optical and electrical crosstalk.